

**PATENT ASSIGNMENT**

Electronic Version v1.1  
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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
Tandon Group, Ltd	06/20/2011
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	Nichols-IP PLLC
<b>Street Address:</b>	740 E. 250 N.
<b>City:</b>	Heber
<b>State/Country:</b>	UTAH
<b>Postal Code:</b>	84032
<b>PROPERTY NUMBERS Total: 3</b>	
<b>Property Type</b>	<b>Number</b>
Patent Number:	6119049
Patent Number:	7238550
Patent Number:	RE39016
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(801)237-0871
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
<b>Phone:</b>	801-414-0750
<b>Email:</b>	snichols@vancott.com
<b>Correspondent Name:</b>	Steven L. Nichols/Vancott PC
<b>Address Line 1:</b>	36 S. State, Suite 1900
<b>Address Line 4:</b>	Salt Lake City, UTAH 84111
<b>ATTORNEY DOCKET NUMBER:</b>	TANDON ASSIGNMENTS
<b>NAME OF SUBMITTER:</b>	Steven L. Nichols
<b>Total Attachments: 1</b> source=TandonAssignment#page1.tif	

**OP \$120.00 6119049**

**ASSIGNMENT**

Whereas, Tandon Group, Ltd, a British Virgin Islands company, having its registered office at Trident Chambers, Wickhams Cay, Road Town, Tortola, British Virgin Islands, wishes to assign and transfer, to NICHOLS-IP PLLC, of the State of Utah having a place of business 740 E. 250 N., Heber UT 84032 U.S.A., ("Assignee"), the entire right, title and interest in:

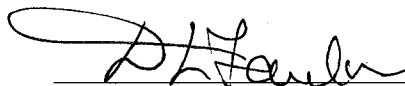
- 1) U.S. Patent No.: 6,119,049, issued on September 12, 2000, and entitled "Memory Module Assembly Using Partially Defective Chips"
- 2) U.S. Reissue Patent No.: RE39,016, issued on March 14, 2006, and entitled "Memory Module Assembly Using Partially Defective Chips"
- 3) U.S. Patent No.: 7,238,550, issued on July 3, 2007, and entitled "Methods and Apparatus for Fabricating Chip-on-Board Modules"

Now, therefore, for valuable consideration furnished by Assignee to Assignor, the receipt and sufficiency of which is hereby acknowledged, the Assignor hereby, without reservation:

- 1. Assigns, transfers, and conveys to Assignee the entire right, title, and interest in and to said inventions and discoveries, said Letters Patents of the United States of America and applications for Letters Patent of the United States of America, any and all other applications for Letters Patent on said inventions and discoveries in whatsoever countries, including all divisional, renewal, substitute, continuation, continuation-in-part, and Convention applications based in whole or in part upon said inventions or discoveries, or upon said applications, and any and all Letters Patent, reissues, reexaminations, and extensions of Letters Patent granted for said inventions and discoveries or upon said applications, and every priority right that is or may be predicated upon or arise from said inventions, said discoveries, said applications, and said Letters Patents, which entire right, title and interest Assignor warrants that it posses and is legally able to assign;
- 2. Authorizes Assignee to file patent applications in any or all countries on any or all of said inventions and discoveries in the name of Assignee or otherwise as Assignee may deem advisable, under the International Convention or otherwise;
- 3. Authorizes and requests the Commissioner of Patents and Trademarks of the United States of America and the empowered officials of all other governments to issue or transfer all said Letters Patents and/or all applications for Letters Patent to Assignee, as assignee of the entire right, title, and interest therein or otherwise as Assignee may direct;

In testimony of which the undersigned, acting for the Assignor, executed this Assignment as an instrument under seal on the date indicated below.

Given and signed this day \_\_\_\_ of the month of \_\_\_\_\_ of the year \_\_\_\_\_.



\_\_\_\_\_  
Signature

Dr. Devinder Tandon  
Chairman